

area **30(a)** to a side of the horizontal portion **26(a)** and that is not covered by the bus member **26** can have connections to a gate.--

IN THE CLAIMS:

Please amend the claims as follows.

1. (Amended) A semiconductor die package comprising:  
a semiconductor die comprising a vertical power transistor, wherein the semiconductor die has a first surface and a second surface;  
a source region at the first surface of the semiconductor die;  
a gate at the first surface of the semiconductor die;  
a drain region at the second surface of the semiconductor die;  
a ground plane proximate the second surface and distal to the first surface;  
and  
a bus member covering a portion of the first surface of the semiconductor die and having at least one leg, wherein the bus member electrically couples the source region of the semiconductor die to the ground plane.

10. (Amended) The semiconductor die of claim 1 wherein the gate is a  
trenched gate.

16. (Amended) A semiconductor die package comprising:  
a semiconductor die comprising a vertical power transistor, wherein the semiconductor die has a first surface and a second surface;  
an emitter region at the first surface of the semiconductor die;  
a base region at the first surface of the semiconductor die;  
a collector region at the second surface of the semiconductor die;  
a ground plane proximate the second surface and distal to the first surface;  
and

a bus member covering a portion of the first surface of the semiconductor die and having at least one leg, wherein the bus member electrically couples the emitter region of the semiconductor die to the ground plane.

18. (Amended) A semiconductor die package comprising:  
a semiconductor die comprising a transistor, wherein the semiconductor die has a first surface and a second surface;  
a source region in the semiconductor die;  
a gate in the semiconductor die;  
a drain region in the semiconductor die;  
a ground plane proximate the second surface and distal to the first surface;  
and

a bus member covering a portion of the first surface of the semiconductor die and having at least one leg, wherein the bus member electrically couples the source region of the semiconductor die to the ground plane.

IN THE DRAWINGS:

Proposed corrections to the Figures are being submitted concurrently herewith in a Request For Approval Of Drawing Correction. The proposed changes are noted in red. A set of formal drawings is also being filed concurrently herewith.

REMARKS

This Amendment is responsive to the Office Action mailed on March 19, 2003.

In this Amendment, claims 1, 10, 16, and 18 are amended to make editorial corrections, and no claims are canceled so that claims 1-19 are pending. Editorial corrections are also made to the specification.